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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/050,334	01/15/2002	Vishnu K. Agarwal	MI22-1913	7861	
21567	7590 08/24/2004		EXAMINER		
WELLS ST. JOHN P.S.			HUYNH, YENNHU B		
601 W. FIRST SPOKANE, V	AVENUE, SUITE 1300 WA 99201		ART UNIT	PAPER NUMBER	
or ordinati,			2813		
			DATE MAILED: 08/24/2004		

Please find below and/or attached an Office communication concerning this application or proceeding.

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1		Application No.	Applicant(s)	A-V-			
	Office Action Summer	10/050,334	AGARWAL ET AL.				
. *	Office Action Summary	Examiner	Art Unit				
		Yennhu B. Huynh	2813				
Period fo	The MAILING DATE of this communication app or Reply	ears on the cover sheet with the c	orrespondence add	ress			
A SH THE - Exte after - If the - If NC - Failu Any	ORTENED STATUTORY PERIOD FOR REPLY MAILING DATE OF THIS COMMUNICATION. nsions of time may be available under the provisions of 37 CFR 1.13 SIX (6) MONTHS from the mailing date of this communication. Properties of the period for reply specified above is less than thirty (30) days, a reply of period for reply is specified above, the maximum statutory period were to reply within the set or extended period for reply will, by statute, reply received by the Office later than three months after the mailing ed patent term adjustment. See 37 CFR 1.704(b).	e6(a). In no event, however, may a reply be tin within the statutory minimum of thirty (30) day ill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this com D (35 U.S.C. § 133).	nmunication.			
Status			•				
1)⊠	Responsive to communication(s) filed on <u>04 Ma</u>	arch 2004.					
		action is non-final.					
3)	,—						
	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.						
Disposit	ion of Claims						
4) 🖂	Claim(s) 16-29 is/are pending in the application	1.					
<i>,</i> —	4a) Of the above claim(s) is/are withdrawn from consideration.						
5) 🗌	Claim(s) is/are allowed.						
6)⊠	⊠ Claim(s) <u>16-29</u> is/are rejected.						
7) 🗌	Claim(s) is/are objected to.						
8) 🗌	Claim(s) are subject to restriction and/or	election requirement.					
Applicat	ion Papers						
9)[]	The specification is objected to by the Examine	f.					
·	O The drawing(s) filed on is/are: a)						
,,_	Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
	Replacement drawing sheet(s) including the correcti			R 1.121(d).			
11)	The oath or declaration is objected to by the Ex	aminer. Note the attached Office	Action or form PTC	D-152.			
Priority (under 35 U.S.C. § 119						
-	Acknowledgment is made of a claim for foreign All b) Some * c) None of: Certified copies of the priority documents Copies of the certified copies of the prior application from the International Bureau	s have been received. s have been received in Applicati ity documents have been receive	on No	itage			
* 5	application from the international Bureau See the attached detailed Office action for a list (` ' ''	ed.				
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Attachmen	• •	, –					
	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948)	4) ∐ Interview Summary Paper No(s)/Mail Da					
3) 🛛 Infor	mation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) r No(s)/Mail Date <u>3/4/04</u> .	5) Notice of Informal P 6) Other:		152)			

DETAILED ACTION

This Office Action is in response to the Amendment 3/4/04.

Claims 1-15 have been cancelled by the Preliminary Amendment filed on 1/15/02

Currently, claims 16-29 are pending.

Information Disclosure Statement

The information disclosure statement filed on 1/15/02, 5/8/02, 3/19/03, 4/2/03 9/23/03, and 3/4/04 are being considered by the examiner.

Specification

Applicant's cooperation is requested in correcting any errors of which applicant may become aware in the specification.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

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Claims 16, 17 & 18 are rejected under 35 U.S.C. 102(e) as being anticipated by Al Shareef et al. (U.S. 6,281,543B1).

The applied reference has common assignees with the instant application.

Based upon the earlier effective U.S. filing date of the reference, it constitutes prior art under 35 U.S.C. 102(e). This rejection under 35 U.S.C. 102(e) might be overcome either by a showing under 37 CFR 1.132 that any invention disclosed but not claimed in the reference was derived from the inventor of this application and is thus not the invention "by another," or by an appropriate showing under 37 CFR 1.131.

Al-Shareef et al. at figs. 1-7 in related art col. 1-7 disclose a high surface capacitor comprising a double layer electrode, which include:

-Re. claim 16: a surface area enhancement layer 142 over a substrate 126, the enhancement layer having an outer surface area per unit area that is greater than an inner surface area per unit area of the enhancement layer (figs. 8-13); a first capacitor electrode layer 144 (combined by 2 layers: barrier layer 146 and electrode 148) over the enhancement layer, the first electrode having an inner surface area per unit area and an outer surface area per unit area that are both greater than an outer surface area per unit area of the substrate, and the first electrode not comprising the enhancement layer; a capacitor dielectric layer 152 over the first electrode 144 and a second capacitor electrode 154 over the dielectric layer (figs. 12 & 13, cols. 5 & 6, lines 29-64).

-Re. claim 17: wherein the first electrode comprised barrier layer is made of TiN (col.2, lines 44-50).

-Re. claim 18: wherein the enhancement layer comprises rugged polysilicon 142 over the substrate 126, the first electrode being over the rugged polysilicon (col. 5, lines 29-34).

Claims 22 & 24-29 are rejected under 35 U.S.C. 102(b) as being anticipated by Fukuzumi et al. (U.S. 6,222,722).

Fukuzmi et al at figs. 1-40 in col. 1-12 disclose a capacitor having undulated lower electrode, which include:

- -Re. claim 22: an opening 22 in an insulative layer 21 over substrate 2, the opening having sides and a bottom (figs. 1-4); a HSG polysilicon layer 23 over the sides of the opening but not over the bottom; a conformal first capacitor electrode 24, the first electrode being sufficiently thin that the first electrode has a rugged outer surface with an outer surface area per unit area greater than an outer surface area per unit area of the substrate underlying the first electrode; a capacitor dielectric layer 26 on the first electrode and a second capacitor electrode layer 27 over the first dielectric (figs. 18-24, col. 13, lines 46-55).
 - -Re. claim 24: wherein the polysilicon comprises spaced apart grains (fig. 20).
- -Re. claim 25: wherein the first electrode comprises barrier layer 17 is made of TiN (col.10, lines 42-65).
- -Re. claim 26: wherein the dielectric layer comprises Ta2O5, ZrO2, BST, HfO2, Al2O3 or ST (col.18, lines 14-18).

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-Re. claim 27: a surface area enhancement layer comprising undoped rugged polysilicon 51 over a substrate 2, the enhancement layer having an outer surface area per unit area that is greater than an inner surface area per unit area of the enhancement layer; a first electrode layer 52 on an in direct contact with the enhancement layer, the first electrode having an inner surface area per unit area and an outer surface area per unit area that are both greater than the inner surface area per unit area of the enhancement layer; a capacitor dielectric layer 53 and an upper capacitor electrode 54 over the dielectric layer (figs. 30-34, col.15 & 16, lines 7-15). In another embodiment, Fukuzumi et al. disclose an enhancement layer 6 contains rugged polisilicon by annealing that can be considered of undoped forming, or any other HSG technology. (col. 7 lines 24-35). Regarding the "undoped of rugged polysilicon" limitation in the claim 27, this is presumed to be inherent to the disclosure of Fukuzumi et al., per MPEP 2112.01, because their disclosed structure is identical to the applicant's structure as claimed in claim 27.

-Re. claim 28: an opening 22 in an insulative layer 21 over substrate 2, the opening having sides and a bottom (fig. 4); a HSG polysilicon layer 23 over the sides of the opening but not over the bottom (figs. 20-24, col. 13, lines 46-55); a conformal first capacitor electrode 7 on the polysilicon 4 convert to HSG layer 6 (fig.4), the first electrode 7 being sufficiently thin that the first electrode has a rugged outer surface with an outer surface area per unit area greater than an outer surface area per unit area of the substrate underlying the first electrode; a capacitor dielectric layer 26 or 8 (col.8)

lines 3) and a second capacitor electrode layer 27 or 9 (col 8 layer 15-19) over the dielectric (fig.24 and fig. 4).

-Re. claim 29: wherein the first electrode also has an inner surface area per unit area that is greater than the surface area per unit area of the sides of the opening area (fig.16, 32 & 34).

Claim Rejections - 35 USC § 103

Regarding claims 19-21 & 23, Applicant's argument overcome rejections.

Previous rejections are withdrawn.

Allowable Subject Matter

Claims 19-21 & 23 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

The following is an examiner's statement of reasons for allowance: Prior art do not suggest or disclose a forming a capacitor, which include an enhancement layer comprises undoped rugged polysilicon, wherein the rugged polysilicon comprises spaced apart grains (claims 19,20 & 23); wherein the outer surface area of the first electrode is at least 30% greater than the substrate outer surface area (claim 21).

The limitations of the above claims 19-21 & 23 are neither anticipated nor rendered obvious over prior art of record.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Response to Arguments

Applicant's arguments filed 3/4/04 have been considered but they are not fully persuasive.

<u>To claims 16-21 & 23 (page 4):</u> Applicant's arguments regarding Al Shareef's reference were those of common ownership.

* It noted that this statement is sufficient to overcome the 35 USC 103 (a) rejection of claims 19-21 & 23. It does not overcome 35 USC 102(e) rejection of claims 16-18.

The applied reference has a common assignee with the instant application. Based upon the earlier effective U.S. filing date of the reference, it constitutes prior art under 35 U.S.C. 102(e). This rejection under 35 U.S.C. 102(e) might be overcome either by a showing under 37 CFR 1.132 that any invention disclosed but not claimed in the reference was derived from the inventor of this application and is thus not the invention "by another," or by an appropriate showing under 37 CFR 1.131.

To claim 22 (p.5): Applicant also argues that the Fukuzumi et al. does not disclose any single capacitor construction that includes each of the claim limitations, and also do not disclose an opening insulative layer and a HSG over the side of the opening but not over the bottom.

Fukuzumi et al. disclose clearly each single capacitor construction that includes limitations cited in the claim 22 (figs. 18-24 col. 11 & 12 lines 41-17). Fukuzumi et al. also disclose an opening insulative layer 21, and having HSG forming over the side of the opening but do not over the bottom (fig. 21, col.11 lines 56-64).

To claim 27 (p.7): Applicant also argues that Fukuzumi et al. does not disclose an enhancement layer containing undoped rugged polysilicon.

* Fukuzumi et al. disclose an enhancement layer 6 contains rugged polysilicon layer 4, wherein the rugged layer formed by annealing that means as of an undoped forming or any other HSG technologies (col.7 lines 24-36).

Regarding the "undoped of rugged polysilicon" limitation in the claim 27, this is presumed to be inherent to the disclosure of Fukuzumi et al., per MPEP 2112.01, because their disclosed structure is identical to the applicant's structure as claimed in claim 27.

To claim 28 (p.9): Applicant also argues that Fukuzumi et al. does not disclose conformal first capacitor electrode on the HSG polysilicon layer but not comprising the HSG polysilicon layer as a part of the first electrode.

* Fukuzumi et al. in another embodiment disclose an opening 5 in an insulative layer over substrate 2, the opening having sides and a bottom (fig. 4); a HSG polysilicon layer 4 convert to the HSG layer 6 over the sides of the opening but not over the bottom (figs. 4, col. 7, lines 36-40); and a conformal first capacitor electrode 7 formed on the HSG polysilicon (fig.4).

Applicant also argues that there is no new ground of rejection.

Examiner clarify that the arguments with respect to claims 16-19,21,23 have been considered but are most in view of the new ground(s) of rejection with Al Shareef et al.

Therefore, this is a final rejection.

Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the

shortened statutory period will expire on the date the advisory action is mailed, and any

extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of

the advisory action. In no event, however, will the statutory period for reply expire later

than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Yennhu B Huynh whose telephone number is 571-272-

1692. The examiner can normally be reached on 8.30AM-7.00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Carl Whitehead, Jr., can be reached on 571-272-1702. The fax phone

numbers for the organization where this application or proceeding is assigned are 703-

308-7722 for regular communications and 703-308-7722 for After Final

communications.

Any inquiry of a general nature or relating to the status of this application or

proceeding should be directed to the receptionist whose telephone number is 703-308-

7724.

YNBH,

8/4/04

CARL WHITEHEAD, JR.

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